

PCN # 1708A1

DATE: May 2, 2019

EXPECTED PCN SHIP DATE: May 2, 2019



Quality Assurance
160 Rio Robles
San Jose, CA 95134

www.maximintegrated.com

PROCESS CHANGE NOTICE

PRODUCT CHANGE NOTICE

MAXIM INTEGRATED HEREBY ISSUES NOTIFICATION OF CHANGE
THAT MAY AFFECT THE FOLLOWING CATEGORIES:

<input type="checkbox"/> DESIGN	<input type="checkbox"/> WAFER FAB	<input checked="" type="checkbox"/> ASSEMBLY	<input type="checkbox"/> TEST	<input type="checkbox"/> ELEC/MECH SPECS
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AFFECTED PRODUCT:

Ordering P/N: (See PN listing XLS in PCN ZIP file)

CHANGE FROM: - Automotive grade products in SOT/SC70 assembled at UTAC THAI LIMITED (UTL) Conductive die attach adhesive Ablebond 84-1LMISR4	CHANGE TO: - Conductive Die Attach Film CDAF515 (applied at assembly manufacturing)
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JUSTIFICATION: -
Changing the process to replace the use of adhesive die attach with Conductive Die Attach Film (CDAF) will improve device quality/reliability by eliminating the risk of a short between die paddle and lead due to the possibility of an excessive adhesive drop-on.
Qualification results are provided in attached report (R28789_R29745).
There is no impact to the form/fit/function of the devices.

TRACEABILITY: Maxim Integrated maintains full traceability by device marking, packaging labels and shipment documents.

Maxim Integrated's Change Notification System is designed to keep our customer base apprised of major product, manufacturing, or facility improvements.

Nasser Ali Chaouche

Nasser AliChaouche / PCN Coordinator

For further information, please contact either of the people listed below.

Contact your local Maxim Integrated Company Representative or Nasser AliChaouche, PCN Coordinator
408-601-5660 / pcn.coordinator@maximintegrated.com